2SC2899

Silicon NPN Triple Diffused

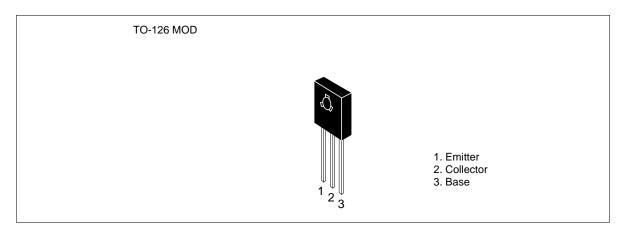
HITACHI

ADE-208-889 (Z) 1st. Edition Sep. 2000

Application

High speed and high voltage switching

Outline



Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	500	V
Collector to emitter voltage	V _{CEO}	400	V
Emitter to base voltage	V_{EBO}	10	V
Collector current	I _c	0.5	А
Collector peak current	I _{C(peak)}	1.0	А
Collector power dissipation	P _c	0.75	W
	P _c *1	10	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at $T_c = 25^{\circ}C$.

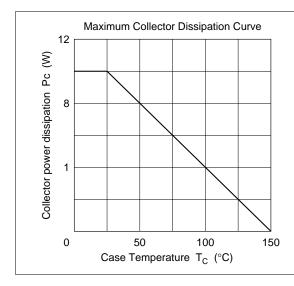


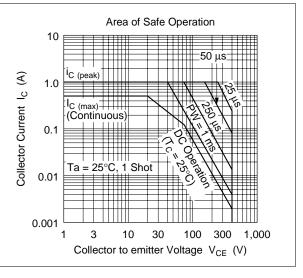
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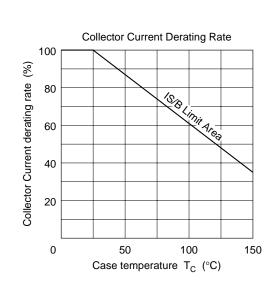
Electrical Characteristics (Ta = 25°C)

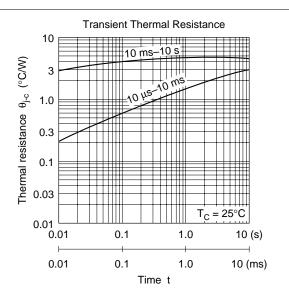
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter sustain voltage	$V_{\text{CEO(sus)}}$	400	_	_	V	$I_{C} = 0.1 \text{ A}, R_{BE} = \infty, L = 100 \text{ mH}$
	V _{CEX(sus)}	400	_	_	V	$I_{C} = 0.5 \text{ A}, I_{B1} = -I_{B2} = 0.1 \text{ A}, \ V_{BE} = -5 \text{ V}, L = 180 \ \mu\text{H}, \ \text{Clamped}$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	10	_	_	V	$I_{\rm E} = 10 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	20	μΑ	$V_{CB} = 400 \text{ V}, I_{C} = 0$
	I _{CEO}	_	_	50	μΑ	$V_{CE} = 350 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h _{FE1}	15	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 0.25 \text{ A}^{*1}$
	h _{FE2}	7	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	1.0	V	$I_{\rm C} = 0.25 \text{ A}, I_{\rm B} = 0.05 \text{ A}^{*1}$
Base to emitter saturation voltage	$V_{\text{BE}(\text{sat})}$	_	_	1.5	V	
Turn on time	t _{on}	_	_	1.0	μs	$I_{\rm C} = 0.5 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 0.1 \text{ A},$
Storage time	t_{stg}	_	_	2.0	μs	V _{cc} ≅ 150 V
Fall time	t _f	_	_	1.0	μs	

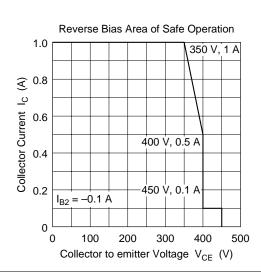
Note: 1. Pulse test

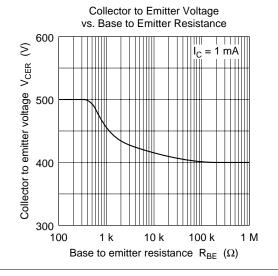


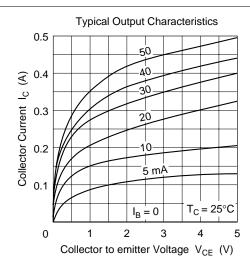


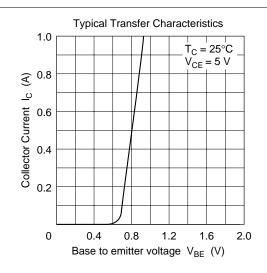


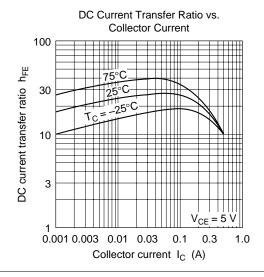


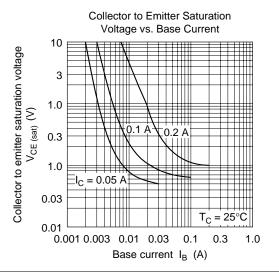


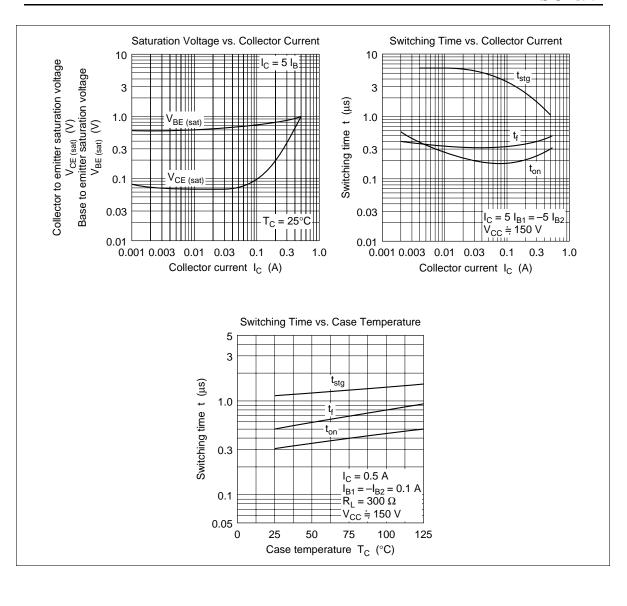




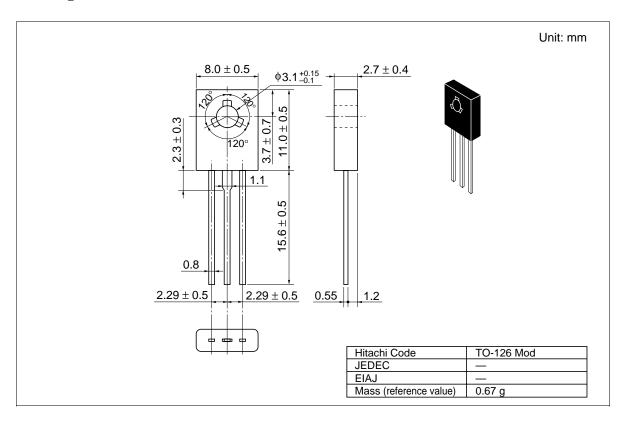








Package Dimensions



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